

Terrablast – Lightweight 35mm Patch Antenna

GGBTP-35.3.A.40

Part No: GGBTP.35.3.A.40

Description: GPS/GLONASS/Galileo/BeiDou 35mm Patch Antenr

Features:

GPS L1 / GLONASS L1 / Galileo E1 / BeiDou B1 Low Profile – 3.5mm Height Pin Type Terrablast Patch Antenna 10g Ultra-Lightweight Patch Peak Gain: 4dBi Efficiency: 70% Ultra-Impact Resistant Low Axial Ratio Dimensions: 35x35x3.72mm Patent Pending Design RoHS & REACH compliant



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1. Introduction



The Terrablast GGBTP.35.3.A.40 is a revolutionary new antenna developed to meet the unique needs of the UAV and automotive industries. It uses a patent pending antenna technology which results in much lighter weight and withstands impacts. The GGBTP.35.3.A.40 weights just 10g, compared with 15.5g for an equivalent ceramic patch antenna. Its impact-resistant characteristics make it ideal for applications such as automotive e-call systems or UAVs, where the antenna's mechanical and electrical integrity should survive after a crash.

The GGBTP.35.3.A.40 is mounted via a pin and double-sided adhesive. This antenna works well without modifications in most environments but can be tuned and further optimized to different ground-planes and enclosures if required. Custom antenna modifications are subject to possible NRE and minimum order quantity.

Terrablast antennas are not suitable for SMD reflow. The correct method is manual soldering at a soldering temperature of 380°C +/- 20°C for a duration of 3 to 5 seconds. All Terrablast antennas undergo rigorous temperature, vibration and impact tests and exceed the highest ISO16750 standards.

For further information, or support to test and integrate Taoglas Terrablast technology please contact your regional Taoglas facility.



Specifications

2.

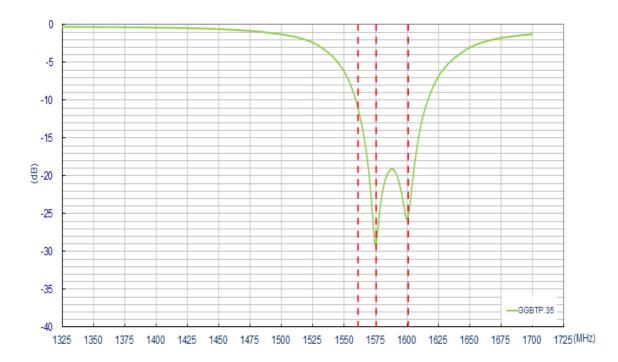
	Electrical		
Application Bands	BeiDou B1	GPS L1	GLONASS L1
Operation Frequency (MHz)	1561	1575.42	1602
Efficiency (%)	72.58	69.81	70.27
Peak Gain (dBi)	4.12	4.03	4.33
Average Gain (dBi)	-1.39	-1.56	-1.53
Impedance		50 ohms	
Return Loss (dB)	<-	10 across operating bands	
Polarization		RHCP	
	Mechanical		
Patch Dimension (mm)		35 x 35 x 3.5	
Pin Diameter (mm)		0.9	
Pin Length (mm)		2.4	
Weight (g)		9.7	
	Environmenta	l	
Storage Temperature		-40°C to 85°C	
Operation Temperature		-40°C to 85°C	
Humidity		Non-Condensing 65°C 95% RH	
	Reliability Testi	ng	
Low Temperature		-40°C, 24hrs	
High Temperature		+85°C, 48hrs	
Temperature Cycling		ISO16750 standard, total 24	Ohrs
Temperature Step		ISO16750 standard, total 300	Omins
Free fall		12m	
Shock		10 shocks per axis on 6 fac	ces
Vibration		ISO16750 standard, 8 hours	/ axis
Pin pull force		>5kg-f	
Production life testing (+105%	C)	AECQ200 standard, total 10	00hrs

* Antenna properties were measured with the antenna mounted on 70*70mm Ground Plane.

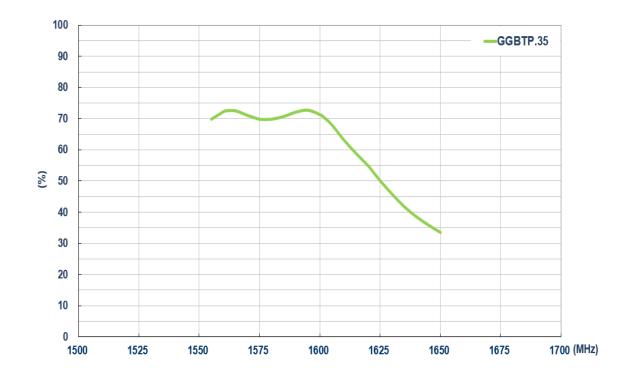




3.



3.2 Efficiency



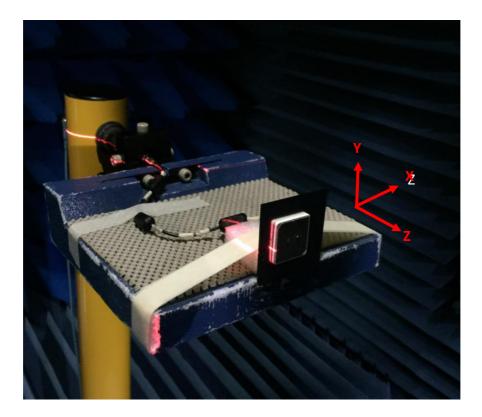










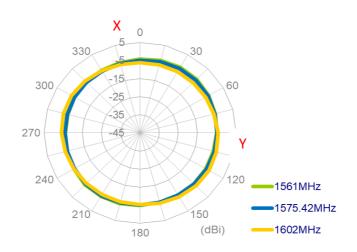


Tested on a 70*70mm ground plane.

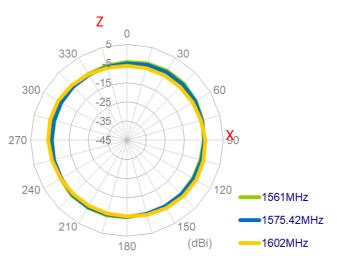


4.2 2D Radiation Patterns

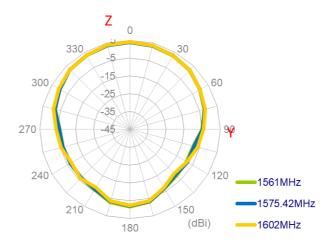
XY Plane



XZ Plane

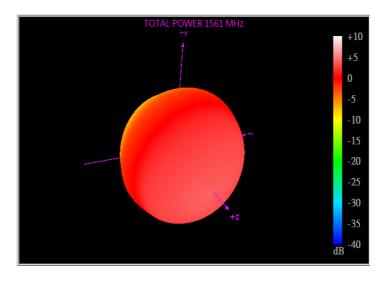


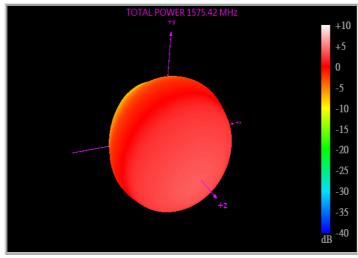
YZ Plane

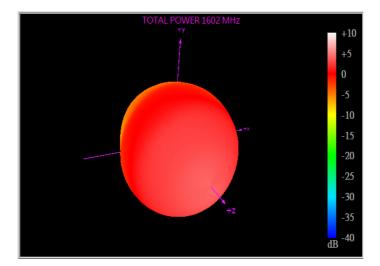




3D Radiation Patterns





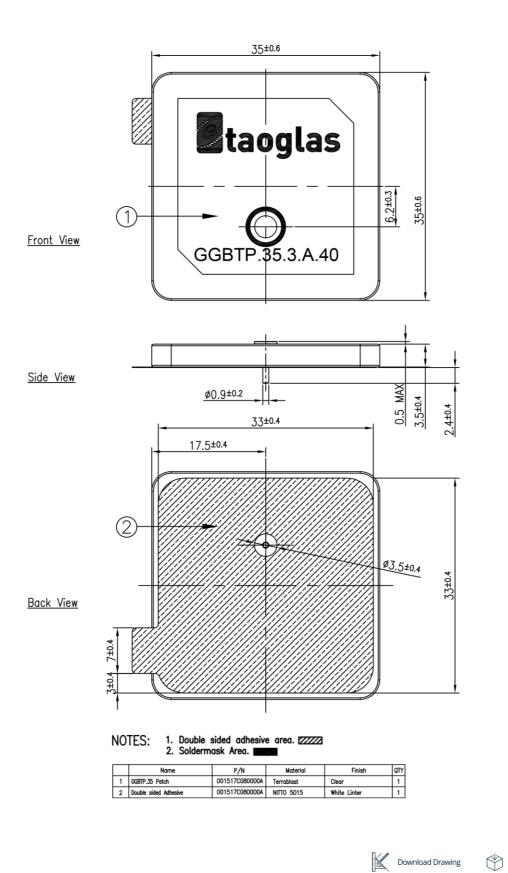


4.3



Mechanical Drawing (Units: mm)

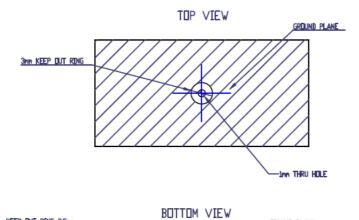
5.

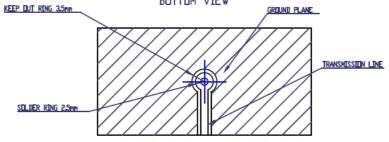


Download 3D Model



6. Footprint







Soldering Method Recommendation

7.1

7.

Manual Hand Soldering

Soldering Temperature: 360-380°C Soldering Duration: 3~4 seconds



7.2

Automated Ferrochrome Soldering Machine

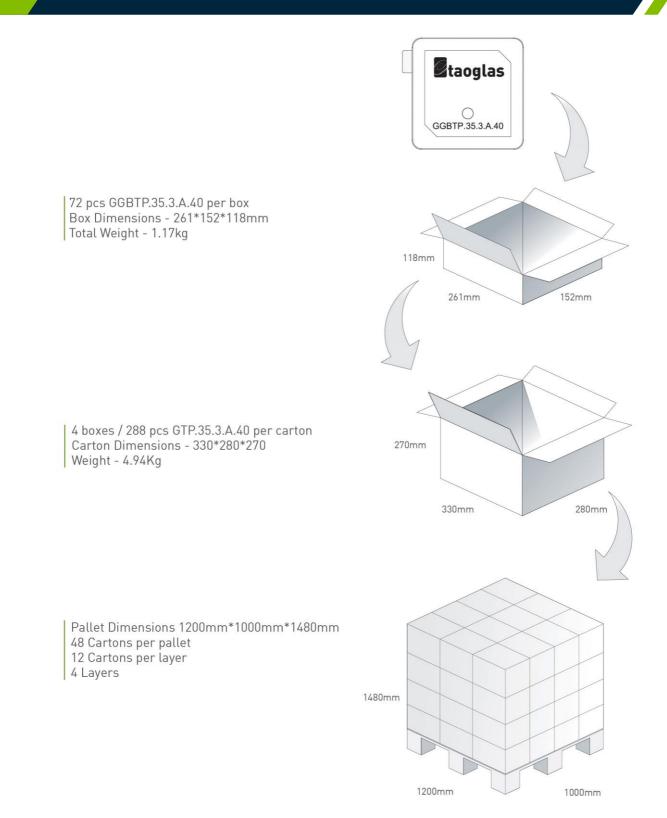
Soldering Temperature: 360-380°C Soldering Duration: 3~4 seconds



Please note that this process will require a one-time fixture to be made for each PCB design, Example as per image above.



8. Packaging





Changelog for the datasheet

SPE-18-8-020 - GGBTP.35.3.A.40

Revision: E (Current	Version)
Date:	2023-01-19
Changes:	Updated footprint drawing.
Changes Made by:	Gary West

Previous Revisions

L	Revision: D		
	Date:	2021-06-12	
	Changes:	Updated Pin Length to 2.4mm Updated Drawing	
	Changes Made by:	Dan Cantwell	

Revision: C		
	Date:	2021-01-19
	Changes:	Updated Packaging
	Changes Made by:	Jack Conroy

Revision: B		
Date:	2020-12-09	
Changes:	Amended soldering recommendations and updated datasheet to new format.	
Changes Made by:	Gary West	

Revision: A (Original First Release)	
Date:	2018-01-17
Notes:	
Author:	WY



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